



IPW
PATENT
8013-1147

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of:

Hirokazu HONDA

Confirmation No. 7187

Serial No. 09/678,609

GROUP 2827

Filed October 4, 2000

Examiner David E. Graybill

MULTILAYER INTERCONNECTION BOARD, SEMICONDUCTOR
DEVICE HAVING THE SAME, AND METHOD OF FORMING
THE SAME AS WELL AS METHOD OF MOUNTING THE
SEMICONDUCTOR CHIP ON THE INTERCONNECTION BOARD

RESPONSE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

August 3, 2004

Sir:

In response to the communication of July 28, 2004,
consideration of the response filed on May 11, 2004 is
respectfully requested.

Remarks begin on page 2 of this paper.